EMI Filter with ESD Protection for Data Line Applications

Product Description

The CM6400 is a 24-bump EMI filter with ESD protection device for data line application in a 0.4 mm pitch, 5 x 5 CSP form factor. It is fully compliant with IEC 61000-4-2 Level 4. The CM6400 is RoHS II compliant.

Features

- 24-Bump, 2.06 mm X 2.06 mm Footprint Chip Scale Package
- These Devices are Pb-Free and are RoHS Compliant

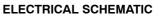


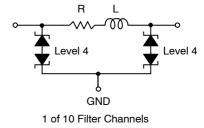
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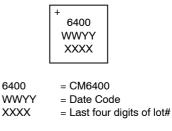


WLCSP24 CASE 567CH





MARKING DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
CM6400	CSP-24 (Pb-Free)	5000/Tape & Reel

+ For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM6400

PACKAGE / PINOUT DIAGRAMS

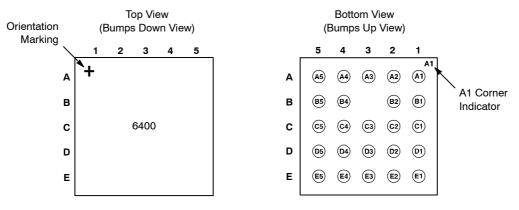


Table 1. PIN DESCRIPTIONS

Pin	Description	Pin	Description
A2 – A5	Channel 1	C4 – C1	Channel 6
A4 – A1	Channel 2	D2 – D5	Channel 7
B2 – B5	Channel 3	D4 – D1	Channel 8
B4 – B1	Channel 4	E2 – E5	Channel 9
C2 – C5	Channel 5	E4 – E1	Channel 10
A3, D3, C3, E3	GND		

ELECTRICAL SPECIFICATIONS AND CONDITIONS

Table 2. PARAMETERS AND OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	-55 to +150	°C
Operating Temperature Range	-40 to +85	°C

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
R	Resistance		100	125	150	Ω
L	Inductance	(Note 2)		24		nH
С	Capacitance per channel	At 1 MHz, V _{IN} = 0 V	23.3	29.2	35	pF
		At 1 MHz, V _{IN} = 2.5 V	14.2	17.8	21.4	pF
Att(5)	Passband attenuation at 5 MHz			-7		dB
F _C	Cut-off frequency	Z_{SOURCE} = 50 Ω, Z_{LOAD} = 50 Ω		200		MHz
V _{BR}	Breakdown voltage	$I_{LOAD} = \pm 10 \text{ mA}$	±6	±6.8	±20	V
I _{LEAK}	Leakage current per channel	V _{IN} = +3.0 V		0.01	0.10	μΑ
	Leakage current per chip	V _{IN} = -3.0 V	-2.0	-0.1		μΑ
V _{ESD}	ESD Peak Discharge Voltage Protection at all pins: a) Contact Discharge per IEC 61000-4-2 standard AND b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±15 ±15			kV

1. All parameters specified at $T_A = 25^{\circ}C$ unless otherwise noted. 2. Standard IEC 61000–4–2 ($C_{Discharge} = 150 \text{ pF}, R_{Discharge} = 330 \Omega$).

CM6400

RF CHARACTERISTICS

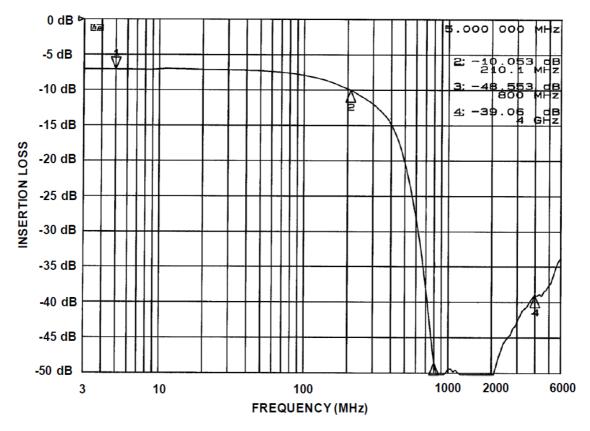
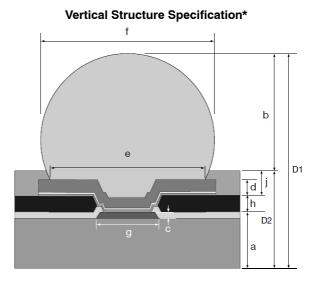


Figure 1. Typical Insertion Loss (Bias = 0 V, T_A = 25°C, 50 Ω Environment)

MECHANICAL SPECIFICATION

Ref.	Parameter	Material	Dimension
а	Die Thickness	Silicon	389 μm
h	Dielectric Layer 1	Polyimide	7.0 μm
j	Dielectric Layer 2	Polyimide	10 µm
	UBM-(Ti/Cu)	Plated Cu	5.0 μm
d		Sputtered Cu	0.4 μm
		Sputtered Ti	0.1 μm
е	UBM Wetting Area Diameter		240 μm
b	Bump Standoff		194 μm
f	Solder Bump Diameter after Bump Reflow		270 μm
с	Metal Pad Height	AlSiCu	1.5 μm
g	Metal Pad Diameter		60 µm
D2			0.406 mm
D1	Finished Thickness		0.600 mm

Table 4. VERTICAL STRUCTURE DIMENSIONS (nominal)



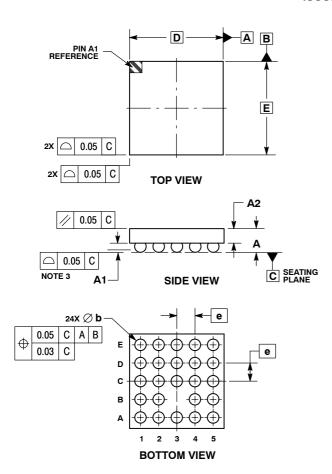


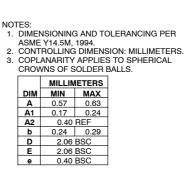
* Daisy Chain CM6040

CM6400

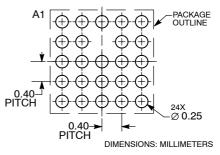
PACKAGE DIMENSIONS

WLCSP24, 2.06x2.06 CASE 567CH-01 ISSUE O





RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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